

ABSTRACT OF THE DISCLOSURE

[0034] A circuit board assembly having a circuit board and a column grid array ("CGA") integrated circuit package. The CGA package has a substrate having an array of solder columns extending from a bottom surface. A frame surrounds the CGA integrated circuit package and is affixed thereto. The frame extends from the substrate to a portion of the circuit board when the column grid array integrated circuit package is mounted on the circuit board to support the column grid array integrated circuit package. The frame is affixed to the CGA integrated circuit package by adhesive after the CGA integrated circuit package is mounted on the circuit board, the adhesive accommodating any variations in height of the CGA integrated circuit package.